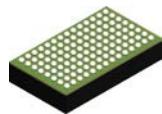


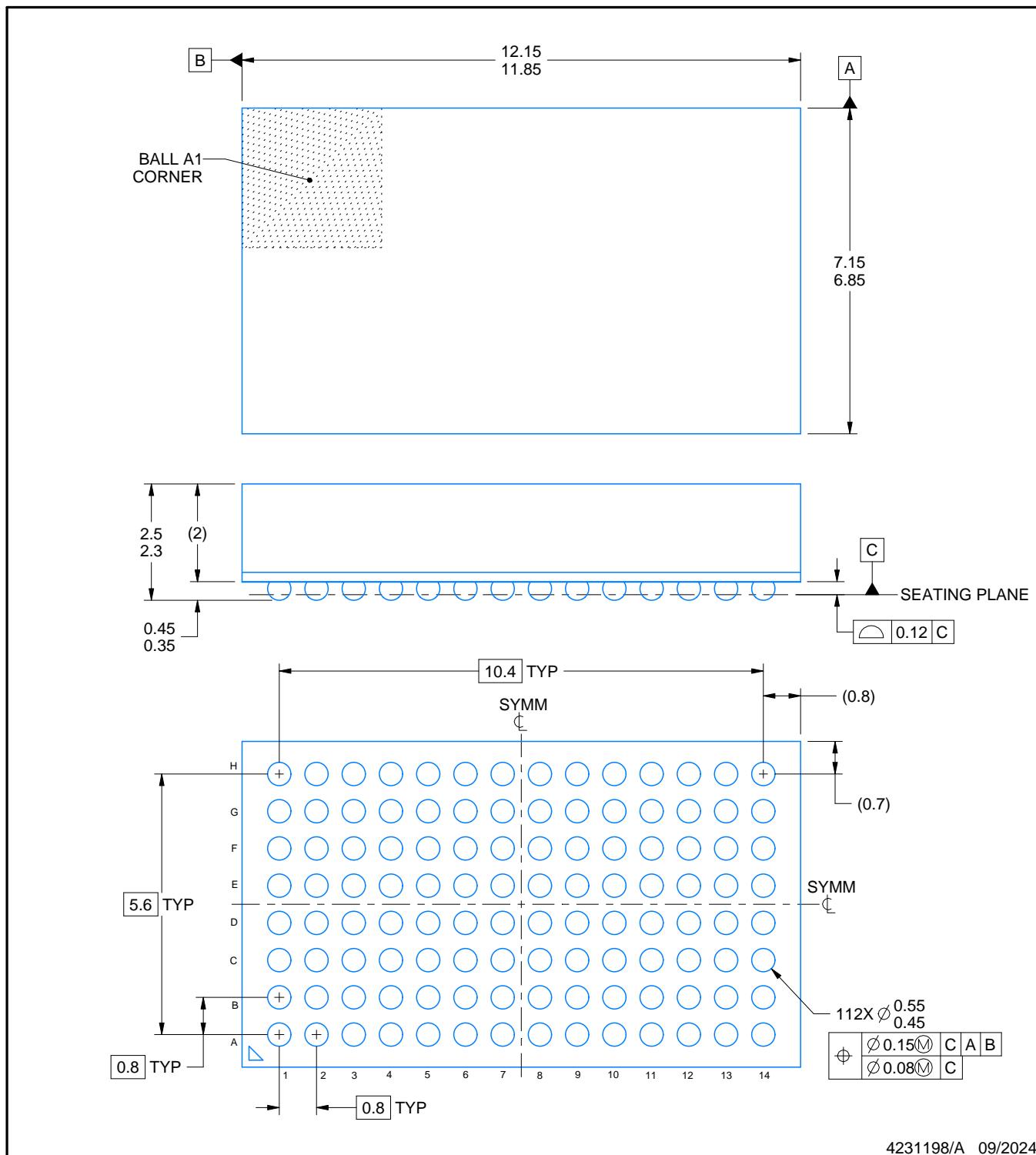
# PACKAGE OUTLINE

APG0112A



FCCSP - 2.5 mm max height

PLASTIC BALL GRID ARRAY



NOTES:

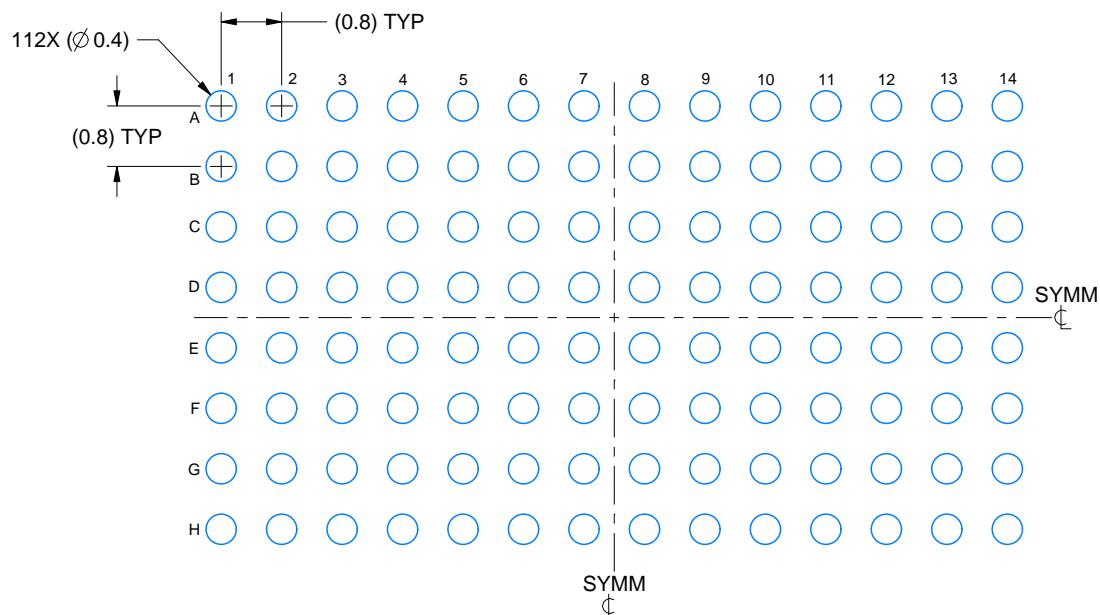
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

## EXAMPLE BOARD LAYOUT

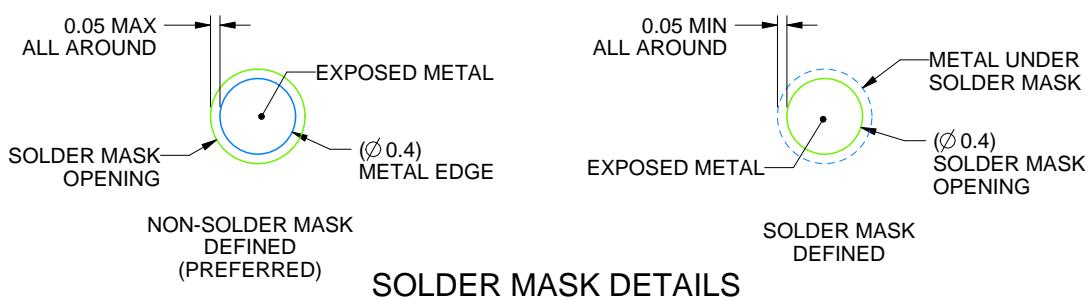
APG0112A

## FCCSP - 2.5 mm max height

## PLASTIC BALL GRID ARRAY



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



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**NOTES: (continued)**

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 ([www.ti.com/lit/spraa99](http://www.ti.com/lit/spraa99)).

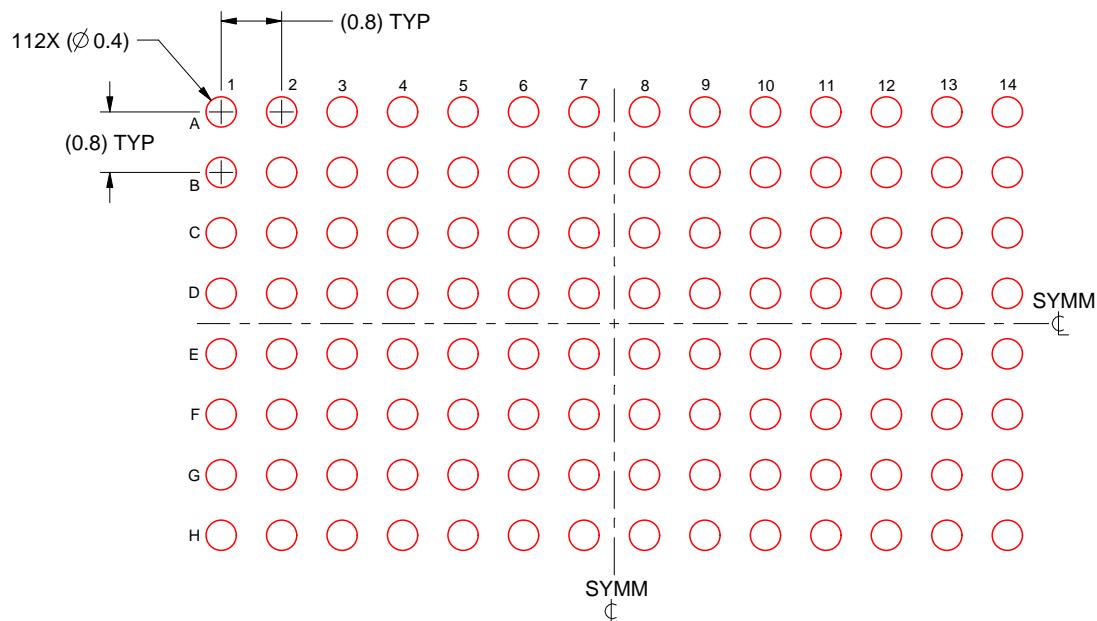
4231198/A 09/2024

# EXAMPLE STENCIL DESIGN

APG0112A

FCCSP - 2.5 mm max height

PLASTIC BALL GRID ARRAY



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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